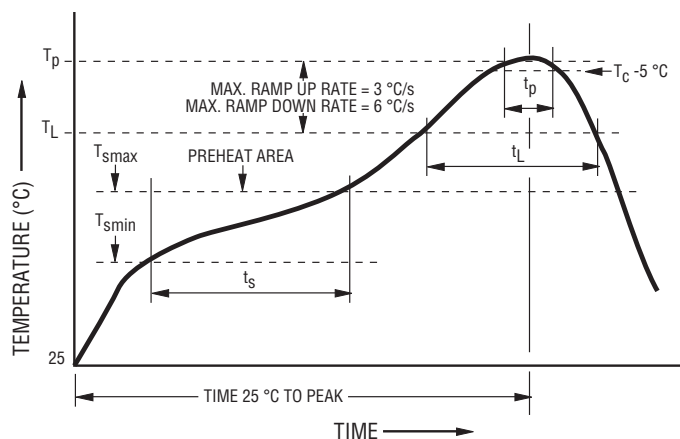


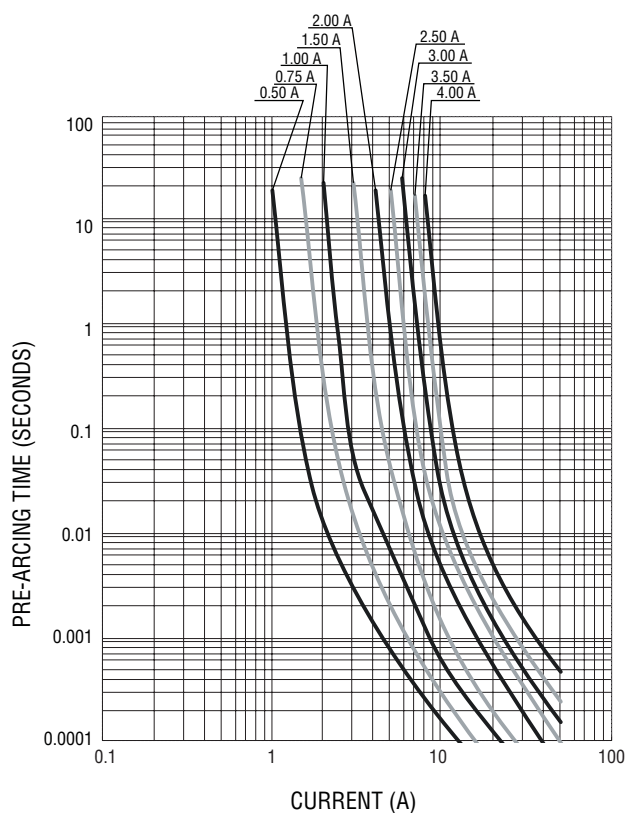
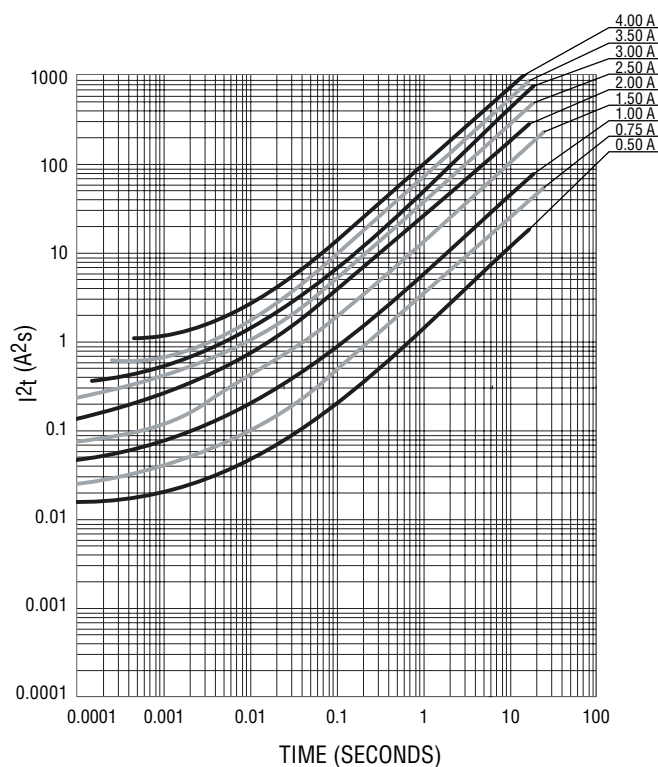
## Solder Reflow Recommendations



| Profile Feature                                                                                                                           | Pb-Free Assembly                   |
|-------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------|
| Preheat / Soak:<br>Temperature Min. ( $T_{smin}$ )<br>Temperature Max. ( $T_{smax}$ )<br>Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ ) | 150 °C<br>200 °C<br>60~120 seconds |
| Ramp Up Rate ( $T_L$ to $T_p$ )                                                                                                           | 3 °C / second max.                 |
| Liquidous Temperature ( $T_L$ )<br>Time ( $t_L$ ) maintained above $T_L$                                                                  | 217 °C<br>60~150 seconds           |
| Peak Package Body Temperature ( $T_p$ )                                                                                                   | 260 °C                             |
| Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )                                                         | 30 seconds*                        |
| Ramp Down Rate ( $T_p$ to $T_L$ )                                                                                                         | 6 °C / second max.                 |
| Time 25 °C to Peak Temperature                                                                                                            | 8 minutes max.                     |

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

## Average Pre-Arcing Time vs. Current Curves

Average  $I^2t$  vs.  $t$  Curves

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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# SF-0603HlxxxF Series Tape and Reel Packaging Specifications

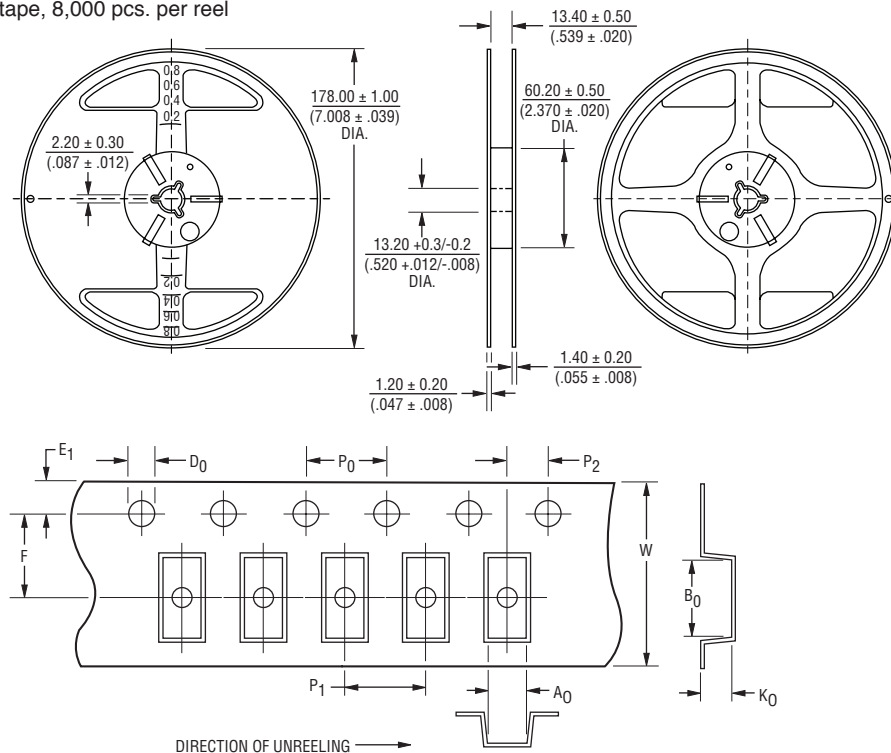
**BOURNS®**

## SF-0603HlxxxF Series per EIA 481-2

### Tape Dimensions

|                |                                         |
|----------------|-----------------------------------------|
| W              | $\frac{8.10 \pm 0.20}{(.319 \pm .008)}$ |
| P <sub>0</sub> | $\frac{4.0 \pm 0.10}{(.157 \pm .004)}$  |
| P <sub>1</sub> | $\frac{4.0 \pm 0.10}{(.157 \pm .004)}$  |
| P <sub>2</sub> | $\frac{2.0 \pm 0.05}{(.079 \pm .002)}$  |
| A <sub>0</sub> | $\frac{1.00 \pm 0.10}{(.039 \pm .004)}$ |
| B <sub>0</sub> | $\frac{1.80 \pm 0.10}{(.071 \pm .004)}$ |
| F              | $\frac{3.50 \pm 0.05}{(.138 \pm .002)}$ |
| E <sub>1</sub> | $\frac{1.75 \pm 0.10}{(.069 \pm .004)}$ |
| D <sub>0</sub> | $\frac{1.55 \pm 0.05}{(.061 \pm .002)}$ |

PACKAGING: Paper tape, 8,000 pcs. per reel



DIMENSIONS:  $\frac{\text{MM}}{(\text{INCHES})}$

REV. A 06/18

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